

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2774313

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHI-SENG LEE	01/23/2014
NAN-HSIUNG TSENG	01/23/2014
CHIN-HONE LIN	01/23/2014
WEI-HAN LAI	01/10/2014
HIDEKAZU MIWA	01/07/2014
JIH-SHENG LAI	01/10/2014
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14166831
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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	03/19/2014
Total Attachments: 2	
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source=49615_assignment#page2.tif	

PATENT

ASSIGNMENT

WHEREAS,

- | | |
|------------------|---------------------|
| 1. Chi-Seng Lee | 2. Nan-Hsiung Tseng |
| 3. Chin-Hone Lin | 4. Wei-Han Lai |
| 5. Hidekazu Miwa | 6. Jih-Sheng Lai |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **DC-DC POWER CONVERSION APPARATUS AND METHOD**

Filed: 2014/01/28 Serial No. 14/166,831

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chi-Seng Lee

Date: Jan 23, 2014

Sole or First Joint Inventor: Chi-Seng Lee

Signature: Nan-Hsiung Tseng

Date: Jan 23, 2014

Second Joint Inventor (if any): Nan-Hsiung Tseng

Signature: Chin-Hone Lin

Date: Jan 23, 2014

Third Joint Inventor (if any): Chin-Hone Lin

Signature: Wei

Date: Jan 10, 2014

Fourth Joint Inventor (if any): Wei-Han Lai

Signature: Hidekazu Miwa

Date: Jan 7 2014

Fifth Joint Inventor (if any): Hidekazu Miwa

Signature: Jih-Sheng Lai

Date: Jan. 10, 2014

Sixth Joint Inventor (if any): Jih-Sheng Lai